P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON) max}	Package	I _D T _A = +25℃
-20V	0.9Ω @ V _{GS} = -4.5V	SOT23	-430mA
-20V	2.0Ω @ V _{GS} = -1.8V	30123	-150mA

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

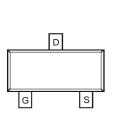
- DC-DC Converters
- Power Management Functions

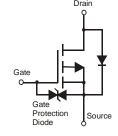
Features

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)} <1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- ESD Protected Gate
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding
- Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
- Solderable per MIL-STD-202, Method 208 (e3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)





Top View

Top View Internal Schematic

Equivalent Circuit

Ordering Information (Note 4)

Part Number Qualification		Case	Packaging
DMP2004K-7	Commercial	SOT23	3,000/Tape & Reel
DMP2004KQ-7	Automotive	SOT23	3,000/Tape & Reel

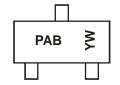
Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

SOT23

- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



PAB = Product Type Marking Code YW = Date Code Marking

Y = Year (ex: W = 2009)

W = Week (ex: $A \sim Z = Weeks 1 \sim 26$ $a \sim v = Weeks 27 \sim 51$

z =Weeks 52 and 53)

Date Code Key

Year	2008	2009	2010	2011	2012	2013	2014	2015
Code	V	W	X	Y	Z	Α	В	С

July 2012

Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V _{DSS}	-20	V
Gate-Source Voltage	V _{GSS}	±8	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	I _D	-600	mA
Pulsed Drain Current	I _{DM}	-1.9	Α

Thermal Characteristics

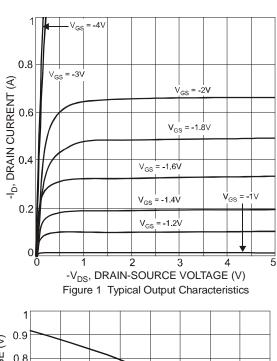
Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_{D}	550	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	227	
Operating and Storage Temperature Range	$T_{J_1}T_{STG}$	-55 to +150	C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		_	-1	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		_	±1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V _{GS(th)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			0.7	0.9	Ω	$V_{GS} = -4.5V$, $I_{D} = -430mA$	
Static Drain-Source On-Resistance	R _{DS (ON)}	_	1.1	1.4		$V_{GS} = -2.5V, I_D = -300mA$	
		_	1,7	2.0		$V_{GS} = -1.8V, I_D = -150mA$	
Forward Transfer Admittance	Y _{fs}	200	_	_	mS	$V_{DS} = -10V, I_{D} = -0.2A$	
Diode Forward Voltage (Note 6)	V_{SD}	-0.5	_	-1.2	V	$V_{GS} = 0V, I_{S} = -115mA$	
DYNAMIC CHARACTERISTICS (Note 7)	ē.						
Input Capacitance	C _{iss}		_	175	pF	101/1/	
Output Capacitance	Coss		_	30	pF	V _{DS} = -16V, V _{GS} = 0V -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	_	20	pF	71 = 1.0WHZ	
Turn-On Delay Time	t _{D(on)}	_	8.5	_	ns	2/ 2// 25//	
Turn-On Rise Time	t _r	_	4.3	_	ns	$V_{DD} = -3V, V_{GS} = -2.5V,$	
Turn-Off Delay Time	t _{D(off)}	_	20.2	_	ns	$R_L = 300\Omega, R_G = 25\Omega,$	
Turn-Off Fall Time	t _f		19.2		ns	$I_{D} = -100 \text{mA}$	

Notes:

- 5. Device mounted on FR-4 PCB.
- 6. Short duration pulse test used to minimize self-heating effect.7. Guaranteed by design. Not subject to product testing.



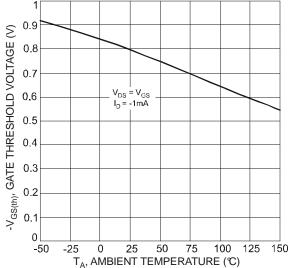
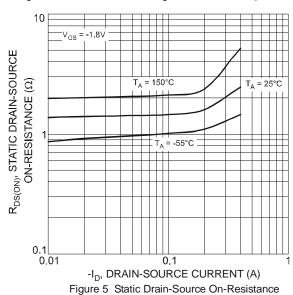
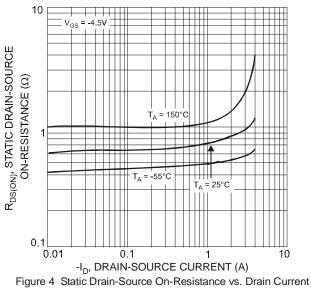


Figure 3 Gate Threshold Voltage vs. Ambient Temperature



vs. Drain Current

1.0 $V_{DS} = 5V$ $T_A = 150^{\circ}C$ 8.0 -I_D, DRAIN CURRENT (A) T_A = -55°C T_A = 25°C 0.2 1 1.5 2
-V_{GS}, GATE-SOURCE VOLTAGE (V)
Figure 2 Typical Transfer Characteristics 0.5 2.5



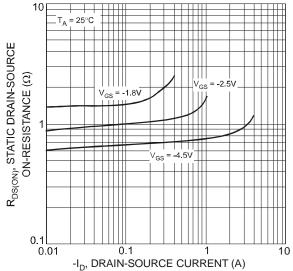


Figure 6 Static Drain-Source On-Resistance vs. **Drain-Source Current**

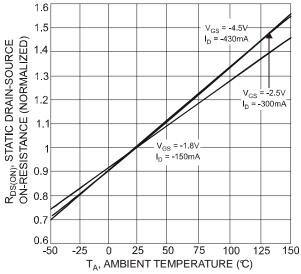


Figure 7 Static Drain-Source On-State Resistance vs. Ambient Temperature

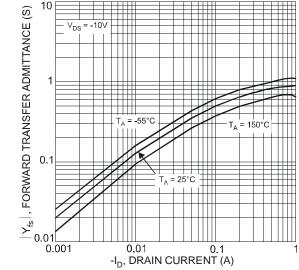


Figure 9 Forward Transfer Admittance vs. Drain Current

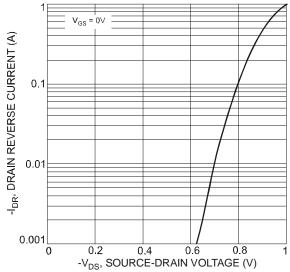
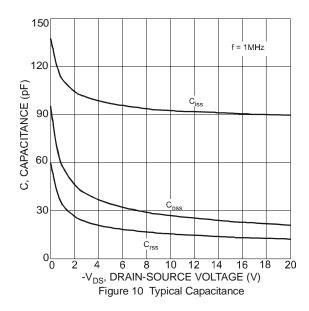
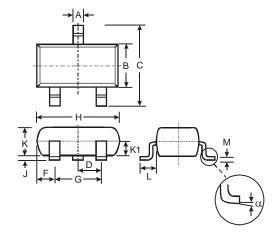


Figure 8 Reverse Drain Current vs. Source-Drain Voltage

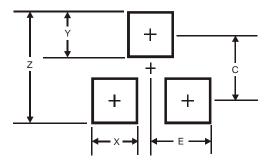


Package Outline Dimensions



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Η	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.903	1.10	1.00		
K1	-	1	0.400		
L	0.45	0.61	0.55		
M	0.085	0.18	0.11		
α	0°	8°	-		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Υ	0.9		
С	2.0		
E	1.35		

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